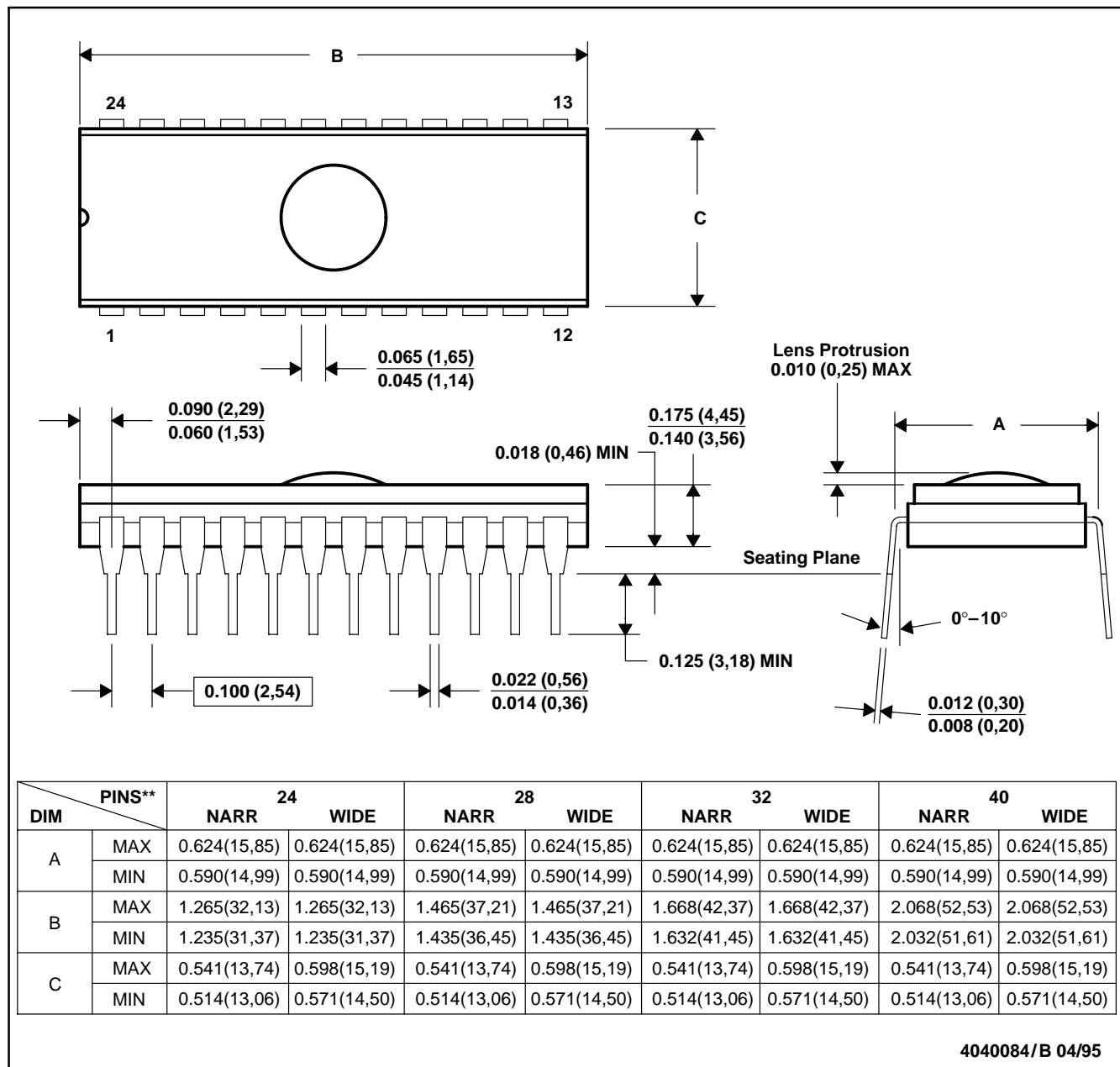


J (R-CDIP-T)****CERAMIC SIDE-BRAZE DUAL-IN-LINE PACKAGE**

24 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.

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